

HybridPACK™ 1 Module

FS400R07A1E3

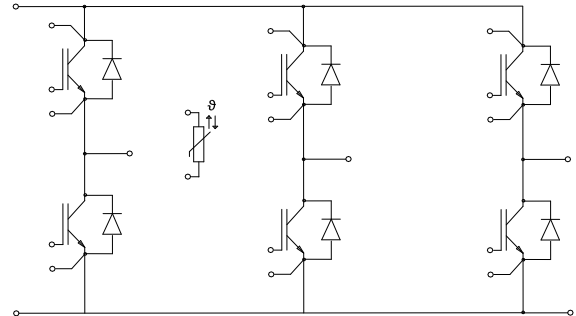
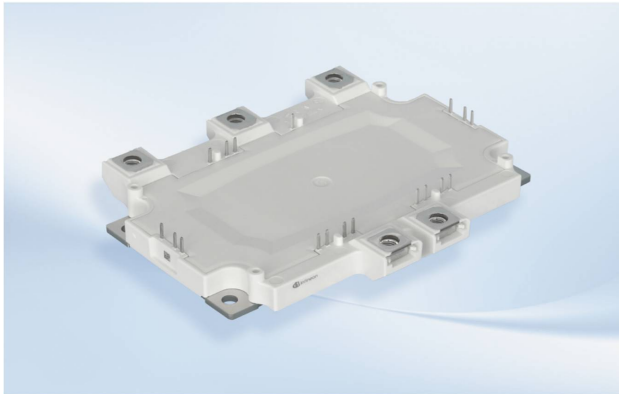
Final Data Sheet

V3.4, 2018-08-09

Automotive High Power

## 1 Features / Description

HybridPACK™ 1 module with Trench/Fieldstop IGBT3 and Emitter Controlled 3 diode and NTC



$V_{CES} = 650V$   
 $I_{C\ nom} = 400A$

### Typical Applications

- Automotive Applications
- Hybrid Electrical Vehicles (H)EV
- Commercial Agriculture Vehicles
- Motor Drives
- Optimized for automotive applications with DC link voltages up to 420 V

### Electrical Features

- Low Switching Losses
- Low  $V_{CESat}$
- $T_{vj\ op} = 150^{\circ}C$
- $V_{CESat}$  with positive Temperature Coefficient

### Mechanical Features

- 2.5kV AC 1min Insulation
- $Al_2O_3$  Substrate with Low Thermal Resistance
- High mechanical robustness
- Integrated NTC temperature sensor
- Copper Base Plate
- RoHS compliant

### Description

Infineon®'s HybridPACK™ 1 is an automotive qualified power module designed for electric vehicle applications for a power range up to 20–30kW. Designed for a 150°C junction operation temperature, the module accommodates a 3-phase Six-Pack configuration of Trench-Field-Stop IGBT3 and matching emitter controlled diodes.

The HybridPACK™ 1 power module is built on Infineon's long time experience in the development of IGBT power modules, intense research efforts of new material combinations and assembly technologies. HybridPACK™ 1 is suitable for air or liquid cooling. The copper base plate combined with high-performance ceramic substrate and Infineon's enhanced wire-bonding process provides unparalleled thermal and power cycling capability and highest reliability for mild hybrid inverter or generator applications. For a compact design the driver stage PCB can easily be soldered on top of the module. All power connections are realized with screw terminals.

Product Name	Ordering Code
FS400R07A1E3	SP000663446

## 2 IGBT, Inverter

### 2.1 Maximum Rated Values

Parameter	Conditions	Symbol	Value	Unit
Collector-emitter voltage	$T_{vj} = 25^{\circ}\text{C}$	$V_{CES}$	650	V
Continuous DC collector current	$T_C = 65^{\circ}\text{C}, T_{vj\text{ max}} = 175^{\circ}\text{C}$ $T_C = 25^{\circ}\text{C}, T_{vj\text{ max}} = 175^{\circ}\text{C}$	$I_{C\text{ nom}}$ $I_C$	400 500	A A
Repetitive peak collector current	$t_P = 1\text{ ms}$	$I_{CRM}$	800	A
Total power dissipation	$T_C = 25^{\circ}\text{C}, T_{vj\text{ max}} = 175^{\circ}\text{C}$	$P_{tot}$	1250	W
Gate-emitter peak voltage		$V_{GES}$	+/-20	V

### 2.2 Characteristic Values

Parameter	Conditions	Symbol	min. typ. max.			Unit	
Collector-emitter saturation voltage	$I_C = 400\text{ A}, V_{GE} = 15\text{ V}$ $I_C = 400\text{ A}, V_{GE} = 15\text{ V}$ $I_C = 400\text{ A}, V_{GE} = 15\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$V_{CE\text{ sat}}$		1.45 1.60 1.70	1.90 V	
Gate threshold voltage	$I_C = 6.40\text{ mA}, V_{CE} = V_{GE}$	$T_{vj} = 25^{\circ}\text{C}$	$V_{GE\text{ th}}$	4.90	5.80	6.50	V
Gate charge	$V_{GE} = -15\text{ V} \dots 15\text{ V}$		$Q_G$		4.30		$\mu\text{C}$
Internal gate resistor		$T_{vj} = 25^{\circ}\text{C}$	$R_{Gint}$		1.0		$\Omega$
Input capacitance	$f = 1\text{ MHz}, V_{CE} = 25\text{ V}, V_{GE} = 0\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$	$C_{ies}$		26.0		nF
Reverse transfer capacitance	$f = 1\text{ MHz}, V_{CE} = 25\text{ V}, V_{GE} = 0\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$	$C_{res}$		0.76		nF
Collector-emitter cut-off current	$V_{CE} = 650\text{ V}, V_{GE} = 0\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$	$I_{CES}$			1.0	mA
Gate-emitter leakage current	$V_{CE} = 0\text{ V}, V_{GE} = 20\text{ V}$	$T_{vj} = 25^{\circ}\text{C}$	$I_{GES}$			400	nA
Turn-on delay time, inductive load	$I_C = 400\text{ A}, V_{CE} = 300\text{ V}$ $V_{GE} = \pm 15\text{ V}$ $R_{Gon} = 1.8\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$t_{d\text{ on}}$		0.10 0.11 0.12		$\mu\text{s}$
Rise time, inductive load	$I_C = 400\text{ A}, V_{CE} = 300\text{ V}$ $V_{GE} = \pm 15\text{ V}$ $R_{Gon} = 1.8\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$t_r$		0.08 0.08 0.08		$\mu\text{s}$
Turn-off delay time, inductive load	$I_C = 400\text{ A}, V_{CE} = 300\text{ V}$ $V_{GE} = \pm 15\text{ V}$ $R_{Goff} = 1.8\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$t_{d\text{ off}}$		0.46 0.50 0.50		$\mu\text{s}$
Fall time, inductive load	$I_C = 400\text{ A}, V_{CE} = 300\text{ V}$ $V_{GE} = \pm 15\text{ V}$ $R_{Goff} = 1.8\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$t_f$		0.05 0.07 0.08		$\mu\text{s}$
Turn-on energy loss per pulse	$I_C = 400\text{ A}, V_{CE} = 300\text{ V}, L_S = 25\text{ nH}$ $V_{GE} = \pm 15\text{ V}, di/dt = 5500\text{ A}/\mu\text{s} (T_{vj} = 150^{\circ}\text{C})$ $R_{Gon} = 1.8\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$E_{on}$		2.90 4.20 4.50		mJ
Turn-off energy loss per pulse	$I_C = 400\text{ A}, V_{CE} = 300\text{ V}, L_S = 25\text{ nH}$ $V_{GE} = \pm 15\text{ V}, du/dt = 3000\text{ V}/\mu\text{s} (T_{vj} = 150^{\circ}\text{C})$ $R_{Goff} = 1.8\ \Omega$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$E_{off}$		13.0 16.0 17.0		mJ
SC data	$V_{GE} \leq 15\text{ V}, V_{CC} = 360\text{ V}$ $V_{CE\text{ max}} = V_{CES} - L_{SCE} \cdot di/dt$	$t_P \leq 8\ \mu\text{s}, T_{vj} = 25^{\circ}\text{C}$ $t_P \leq 6\ \mu\text{s}, T_{vj} = 150^{\circ}\text{C}$	$I_{SC}$		2800 2000		A
Thermal resistance, junction to case	per IGBT		$R_{thJC}$			0.120	K/W
Thermal resistance, case to heatsink	per IGBT $\lambda_{\text{Paste}} = 1\text{ W}/(\text{m}\cdot\text{K}) / \lambda_{\text{grease}} = 1\text{ W}/(\text{m}\cdot\text{K})$		$R_{thCH}$		0.080		K/W
Temperature under switching conditions	$t_{op}$ continuous		$T_{vj\text{ op}}$	-40		150	$^{\circ}\text{C}$

### 3 Diode, Inverter

#### 3.1 Maximum Rated Values

Parameter	Conditions	Symbol	Value	Unit
Repetitive peak reverse voltage	$T_{vj} = 25^{\circ}\text{C}$	$V_{RRM}$	650	V
Continuous DC forward current		$I_F$	400	A
Repetitive peak forward current	$t_P = 1 \text{ ms}$	$I_{FRM}$	800	A
$I^2t$ - value	$V_R = 0 \text{ V}, t_P = 10 \text{ ms}, T_{vj} = 125^{\circ}\text{C}$ $V_R = 0 \text{ V}, t_P = 10 \text{ ms}, T_{vj} = 150^{\circ}\text{C}$	$I^2t$	8800 8500	$\text{A}^2\text{s}$ $\text{A}^2\text{s}$

#### 3.2 Characteristic Values

Parameter	Conditions	Symbol	Value			Unit
			min.	typ.	max.	
Forward voltage	$I_F = 400 \text{ A}, V_{GE} = 0 \text{ V}$ $I_F = 400 \text{ A}, V_{GE} = 0 \text{ V}$ $I_F = 400 \text{ A}, V_{GE} = 0 \text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$V_F$	1.55 1.50 1.45	1.95	V
Peak reverse recovery current	$I_F = 400 \text{ A}, -di_F/dt = 5500 \text{ A}/\mu\text{s} (T_{vj} = 150^{\circ}\text{C})$ $V_R = 300 \text{ V}$ $V_{GE} = -15 \text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$I_{RM}$	210 280 300		A
Recovered charge	$I_F = 400 \text{ A}, -di_F/dt = 5500 \text{ A}/\mu\text{s} (T_{vj} = 150^{\circ}\text{C})$ $V_R = 300 \text{ V}$ $V_{GE} = -15 \text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$Q_r$	18.0 30.0 34.0		$\mu\text{C}$
Reverse recovery energy	$I_F = 400 \text{ A}, -di_F/dt = 5500 \text{ A}/\mu\text{s} (T_{vj} = 150^{\circ}\text{C})$ $V_R = 300 \text{ V}$ $V_{GE} = -15 \text{ V}$	$T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 150^{\circ}\text{C}$	$E_{rec}$	3.60 7.25 8.30		mJ
Thermal resistance, junction to case	per diode		$R_{thJC}$		0.200	K/W
Thermal resistance, case to heatsink	per diode $\lambda_{Paste} = 1 \text{ W}/(\text{m}\cdot\text{K}) / \lambda_{grease} = 1 \text{ W}/(\text{m}\cdot\text{K})$		$R_{thCH}$	0.085		K/W
Temperature under switching conditions	$t_{op}$ continuous		$T_{vj op}$	-40	150	$^{\circ}\text{C}$

### 4 NTC-Thermistor

Parameter	Conditions	Symbol	Value			Unit
			min.	typ.	max.	
Rated resistance	$T_C = 25^{\circ}\text{C}$	$R_{25}$		5.00		$\text{k}\Omega$
Deviation of $R_{100}$	$T_C = 100^{\circ}\text{C}, R_{100} = 493 \Omega$	$\Delta R/R$	5		5	%
Power dissipation	$T_C = 25^{\circ}\text{C}$	$P_{25}$			20.0	mW
B-value	$R_2 = R_{25} \exp [B_{25/50}(1/T_2 - 1/(298,15 \text{ K}))]$	$B_{25/50}$		3375		K
B-value	$R_2 = R_{25} \exp [B_{25/80}(1/T_2 - 1/(298,15 \text{ K}))]$	$B_{25/80}$		3411		K
B-value	$R_2 = R_{25} \exp [B_{25/100}(1/T_2 - 1/(298,15 \text{ K}))]$	$B_{25/100}$		3433		K

Specification according to the valid application note.

## 5 Module

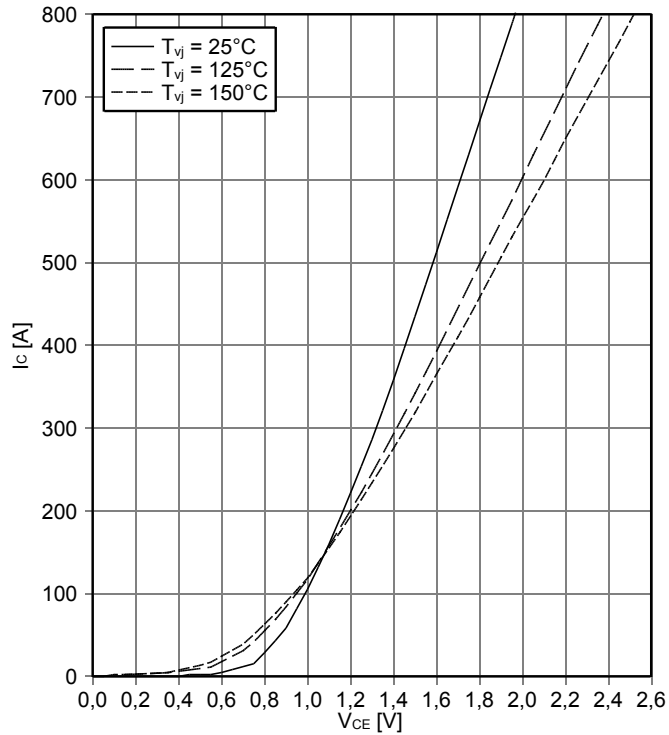
Parameter	Conditions	Symbol	Value			Unit
Isolation test voltage	RMS, f = 50 Hz, t = 1 min.	$V_{ISOL}$	2.5			kV
Material of module baseplate			Cu			
Internal isolation	basic insulation (class 1, IEC 61140)		Al <sub>2</sub> O <sub>3</sub>			
Creepage distance	terminal to heatsink	$d_{Creep}$	12.0			mm
	terminal to terminal		6.1			
Clearance	terminal to heatsink	$d_{Clear}$	12.0			mm
	terminal to terminal		6.1			
Comperative tracking index		CTI	> 200			
			min.	typ.	max.	
Stray inductance module		$L_{sCE}$		30		nH
Module lead resistance, terminals - chip	$T_C = 25\text{ °C}$ , per switch	$R_{CC+EE}$		1.00		mΩ
Storage temperature		$T_{stg}$	-40		125	°C
Mounting torque for modul mounting	Screw M5 baseplate to heatsink	M	3.00		6.00	Nm
Terminal connection torque	Screw M6	M	3.0	-	6.0	Nm
Weight		G		485		g

Der Kollektor-Dauergleichstrom / Dioden-Dauergleichstrom ist durch die Lastanschlüsse begrenzt.  
DC-collector current / diode forward current limited by power terminals.

## 6 Characteristics Diagrams

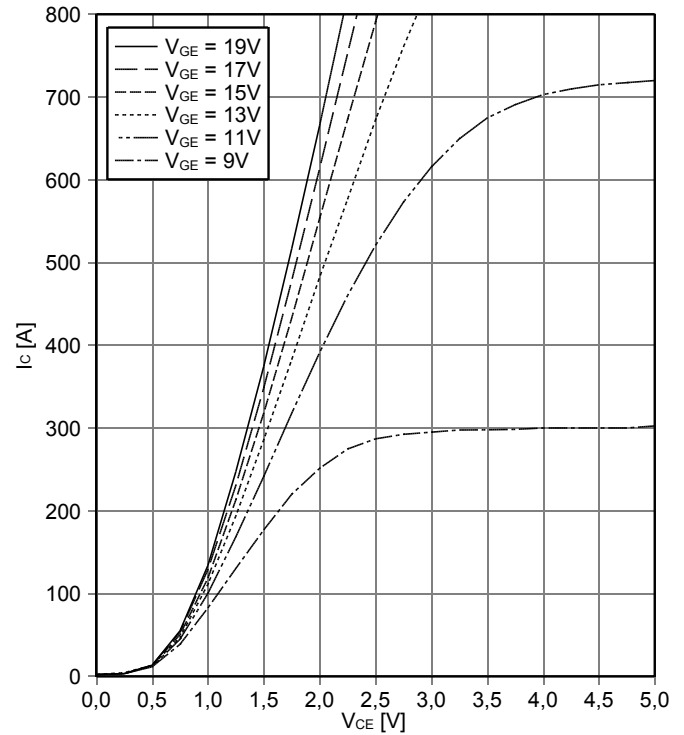
**output characteristic IGBT, Inverter (typical)**

$I_C = f(V_{CE})$   
 $V_{GE} = 15\text{ V}$



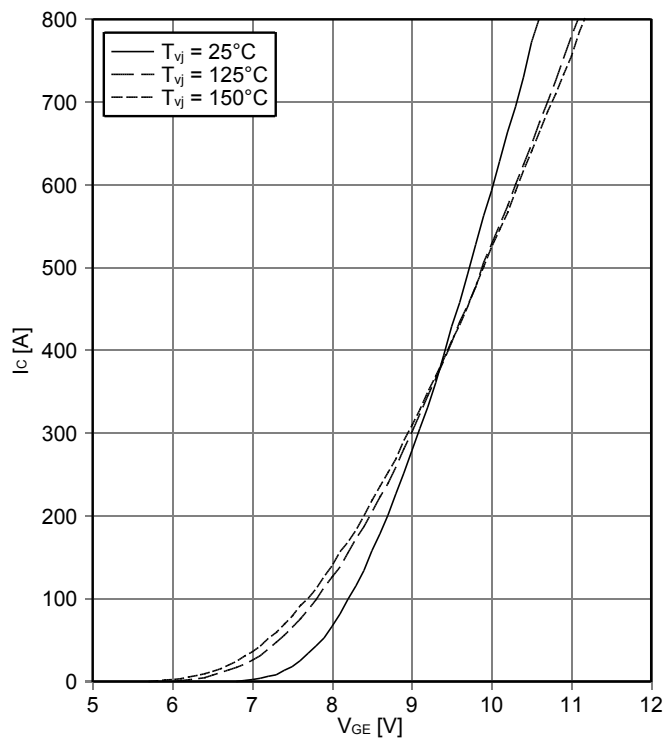
**output characteristic IGBT, Inverter (typical)**

$I_C = f(V_{CE})$   
 $T_{vj} = 150^\circ\text{C}$



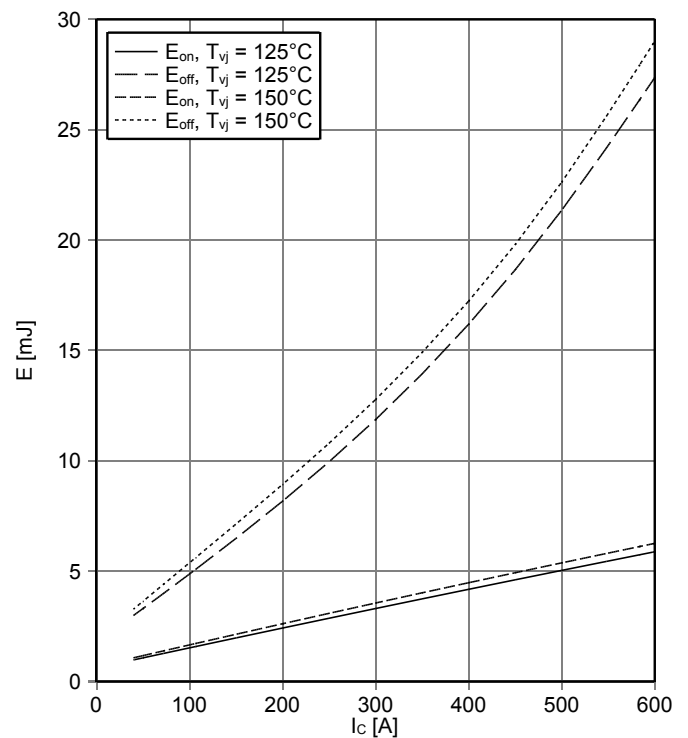
**transfer characteristic IGBT, Inverter (typical)**

$I_C = f(V_{GE})$   
 $V_{CE} = 20\text{ V}$



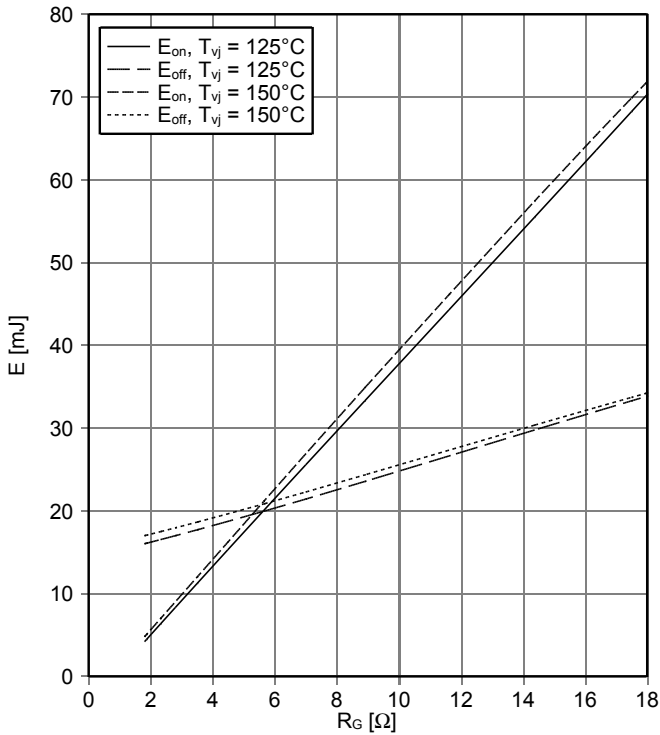
**switching losses IGBT, Inverter (typical)**

$E_{on} = f(I_C)$ ,  $E_{off} = f(I_C)$   
 $V_{GE} = \pm 15\text{ V}$ ,  $R_{Gon} = 1.8\ \Omega$ ,  $R_{Goff} = 1.8\ \Omega$ ,  $V_{CE} = 300\text{ V}$



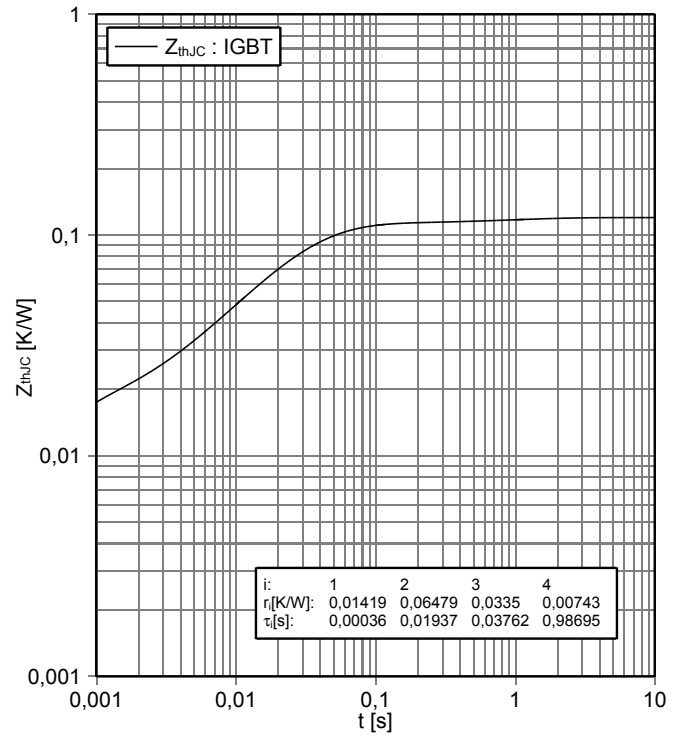
**switching losses IGBT, Inverter (typical)**

$E_{on} = f(R_G), E_{off} = f(R_G)$   
 $V_{GE} = \pm 15\text{ V}, I_C = 400\text{ A}, V_{CE} = 300\text{ V}$



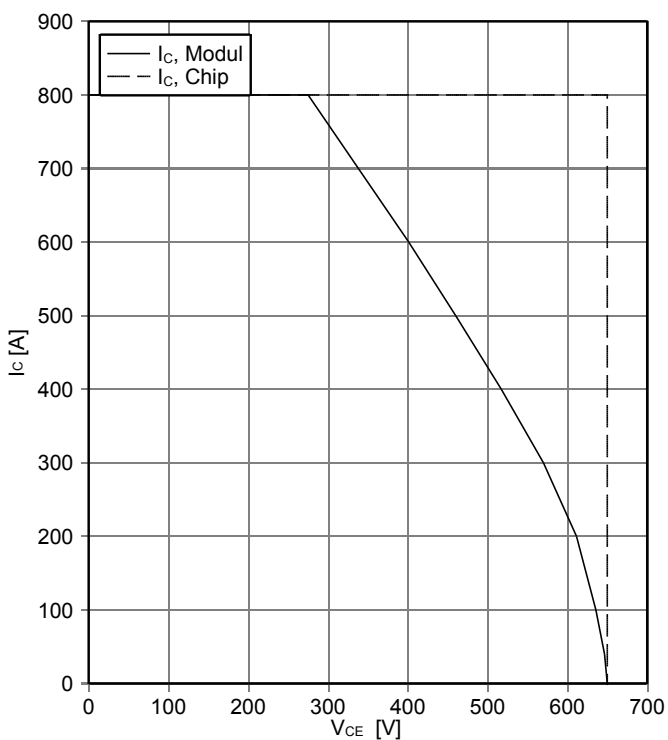
**transient thermal impedance IGBT, Inverter**

$Z_{thJC} = f(t)$



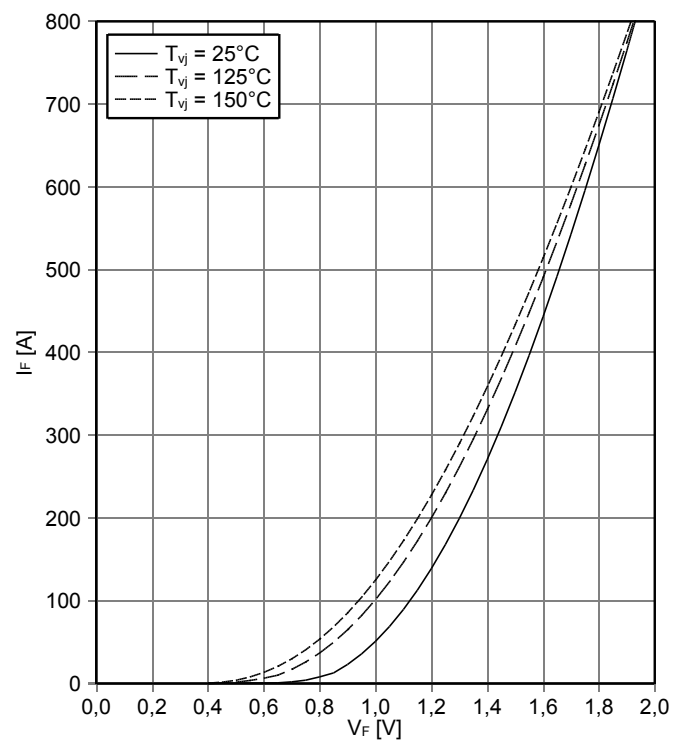
**reverse bias safe operating area IGBT, Inverter (RBSOA)**

$I_C = f(V_{CE})$   
 $V_{GE} = \pm 15\text{ V}, R_{Goff} = 1.8\ \Omega, T_{vj} = 150^\circ\text{C}$



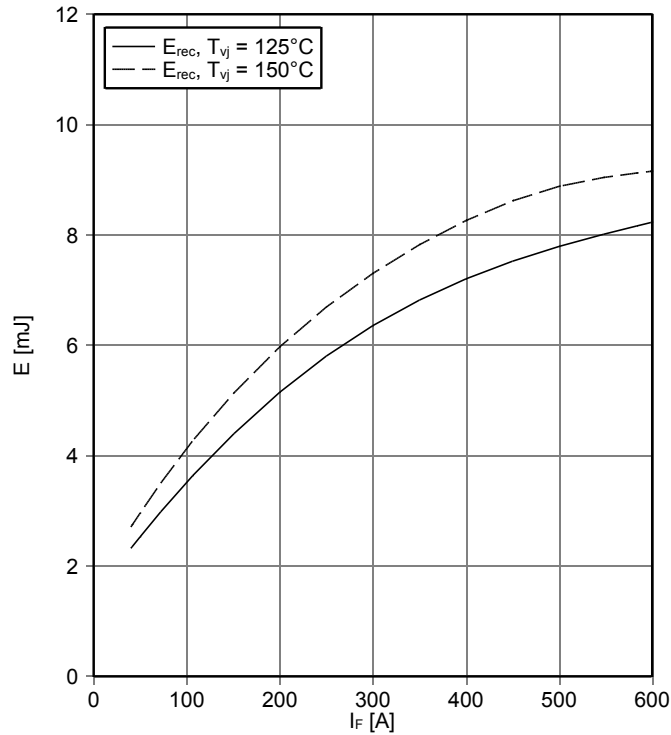
**forward characteristic of Diode, Inverter (typical)**

$I_F = f(V_F)$



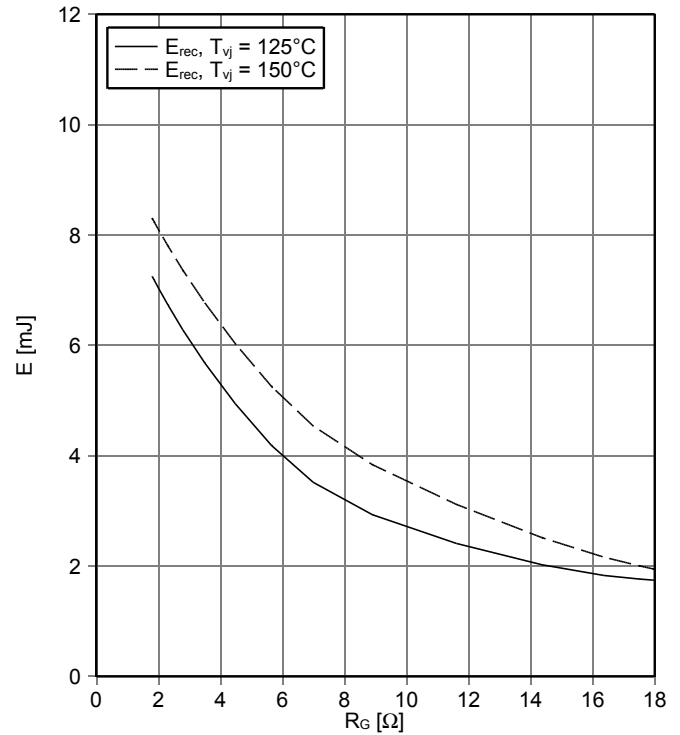
**switching losses Diode, Inverter (typical)**

$E_{rec} = f(I_F)$   
 $R_{Gon} = 1.8 \Omega, V_{CE} = 300 V$



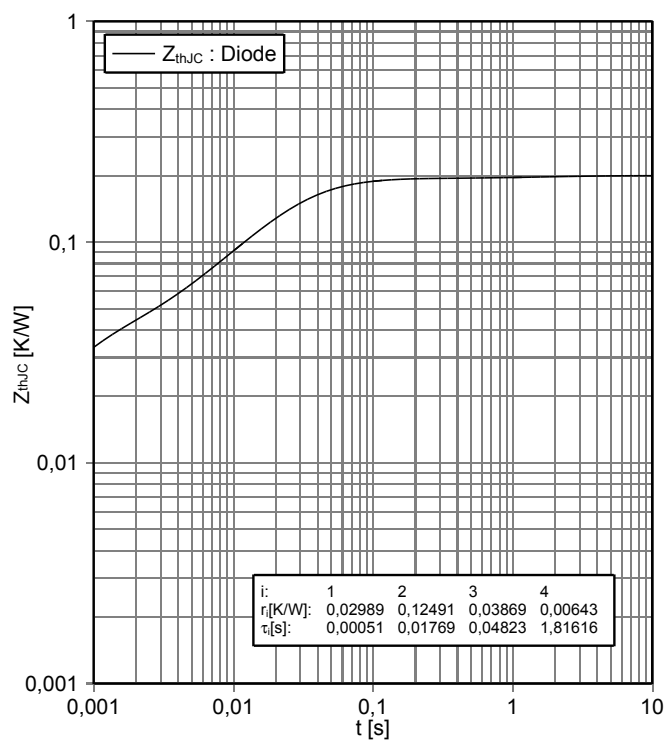
**switching losses Diode, Inverter (typical)**

$E_{rec} = f(R_G)$   
 $I_F = 400 A, V_{CE} = 300 V$



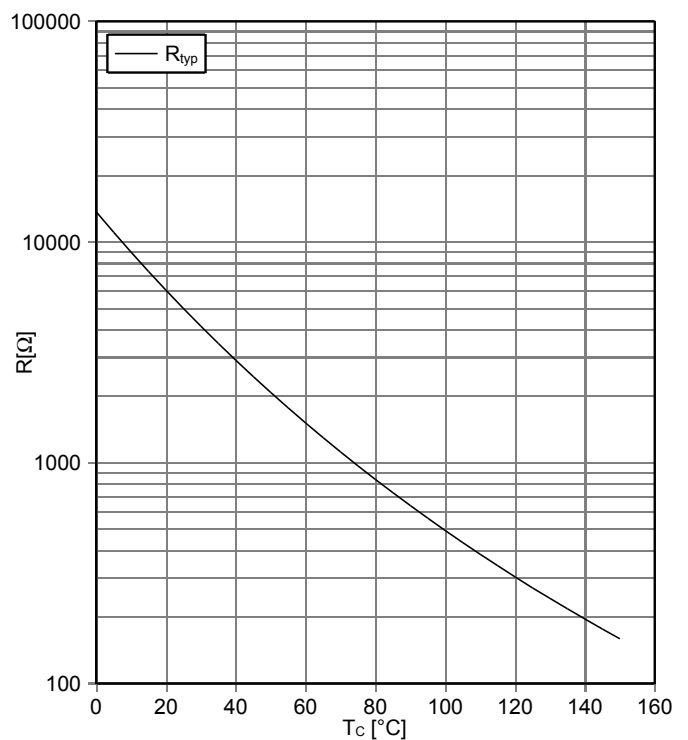
**transient thermal impedance Diode, Inverter**

$Z_{thJC} = f(t)$



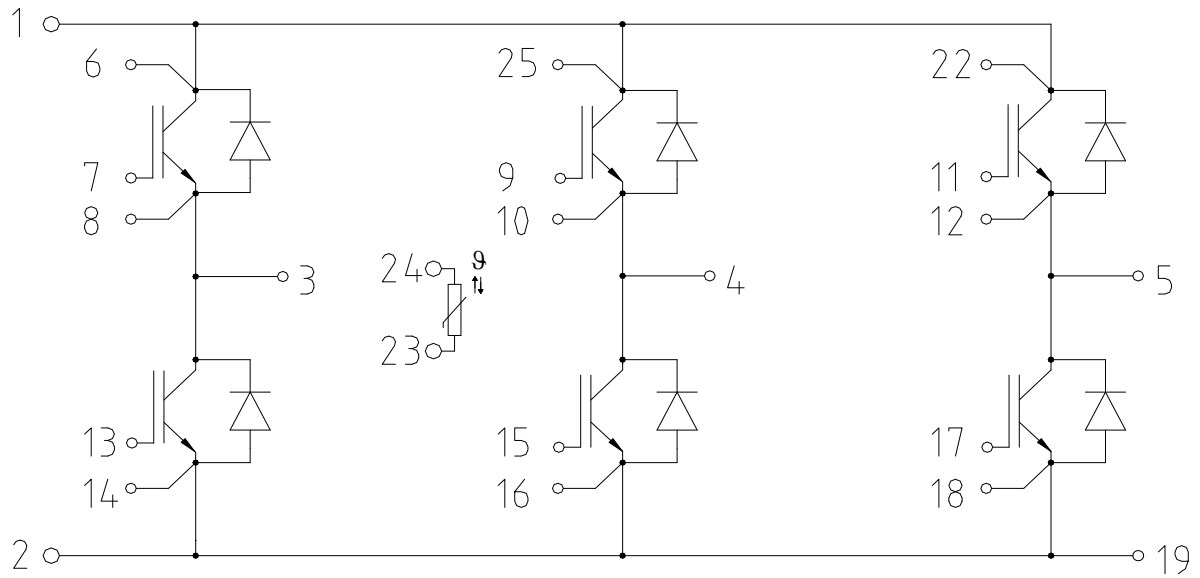
**NTC-Thermistor-temperature characteristic (typical)**

$R = f(T)$

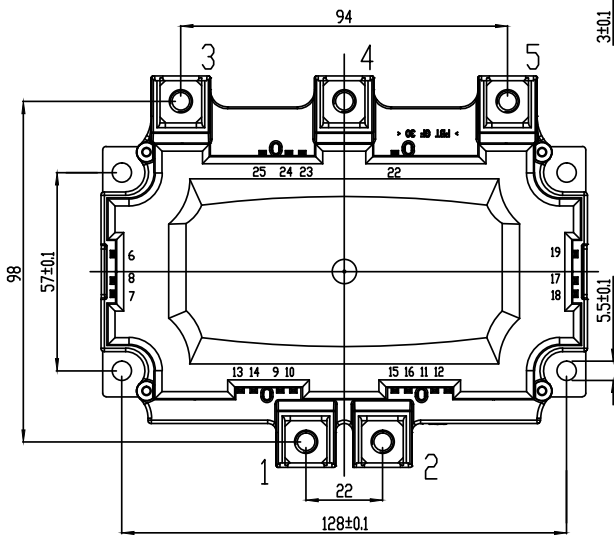
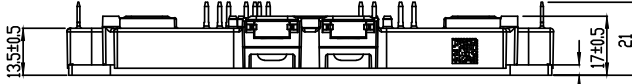




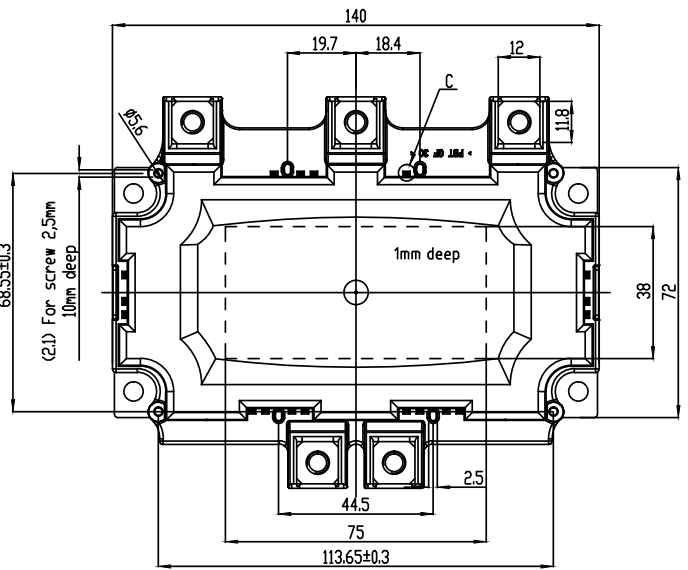
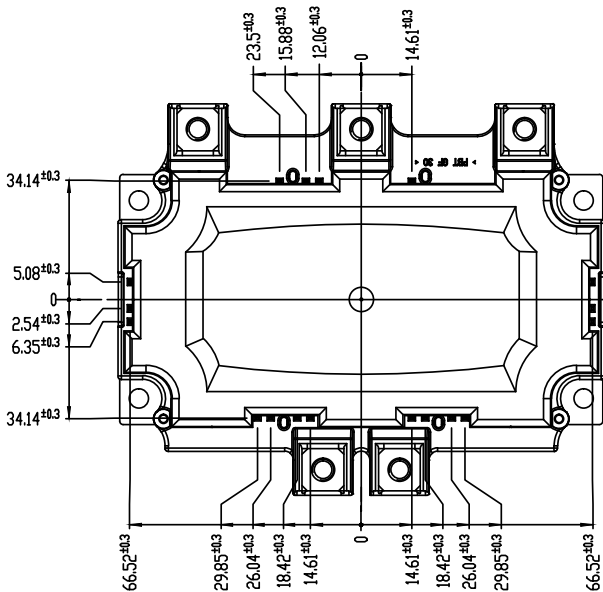
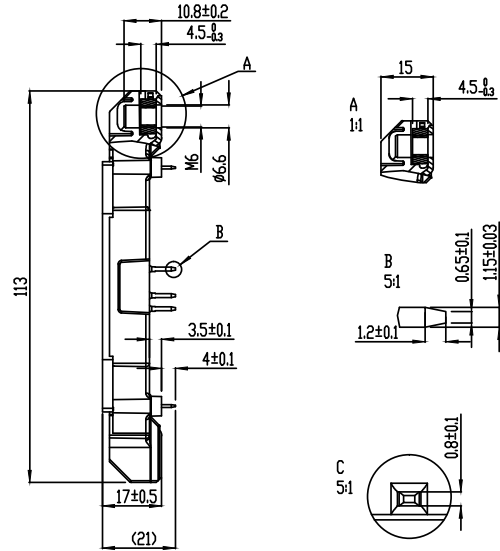
**7 Circuit diagram**



**8 Package outlines**




All dimensions are to be measured in the mounted condition




## 9 Label Codes

### 9.1 Module Code

<b>Code Format</b>	Data Matrix		
<b>Encoding</b>	ASCII Text		
<b>Symbol Size</b>	16x16		
<b>Standard</b>	IEC24720 and IEC16022		
<b>Code Content</b>	<b>Content</b> Module Serial Number Module Material Number Production Order Number Datecode (Production Year) Datecode (Production Week)	<b>Digit</b> 1 - 5 6 - 11 12 - 19 20 - 21 22 - 23	<b>Example (below)</b> 71549 142846 55054991 15 30
<b>Example</b>	 71549142846550549911530		

### 9.2 Packing Code

<b>Code Format</b>	Code128			
<b>Encoding</b>	Code Set A			
<b>Symbol Size</b>	34 digits			
<b>Standard</b>	IEC8859-1			
<b>Code Content</b>	<b>Content</b> Backend Construction Number Production Lot Number Serial Number Date Code Box Quantity	<b>Identifier</b> X 1T S 9D Q	<b>Digit</b> 2 - 9 12 - 19 21 - 25 28 - 31 33 - 34	<b>Example (below)</b> 95056609 2X0003E0 754389 1139 15
<b>Example</b>	 X950566091T2X0003E0S754389D1139Q15			

## Revision History

Major changes since previous revision

---

### Revision History

Reference	Date	Description
V1.0	2009-08-26	Initial Version
V1.1	2009-10-14	target data
V2.0	2009-11-19	preliminary data
V3.0	2010-04-21	final data
V3.1	2012-02-29	final data
V3.2	2016-11-08	new datasheet format
V3.3	2017-03-07	-
V3.4	2018-08-09	update of "Terms & Conditions of usage"

## Terms & Conditions of usage

Edition 2018-08-01

Published by  
**Infineon Technologies AG**  
**81726 Munich, Germany**  
 © 2018 Infineon Technologies AG  
 All Rights Reserved.

### Legal Disclaimer

The information given in this document shall in no event be regarded as a guarantee of conditions or characteristics. With respect to any examples or hints given herein, any typical values stated herein and/or any information regarding the application of the device, Infineon Technologies hereby disclaims any and all warranties and liabilities of any kind, including without limitation, warranties of non-infringement of intellectual property rights of any third party.

### Information

For further information on technology, delivery terms and conditions and prices, please contact the nearest Infineon Technologies Office (<http://www.infineon.com>)

### Warnings

Due to technical requirements, components may contain dangerous substances. For information on the types in question, please contact the nearest Infineon Technologies Office.

These components are not designed for "special applications" that demand extremely high reliability or safety such as aerospace, defense or life support devices or systems (Class III medical devices). If you intend to use the components in any of these special applications, please contact your local representative at International Rectifier HiRel Products, Inc. or the Infineon support (<https://www.infineon.com/support>) to review product requirements and reliability testing.

Infineon Technologies components may be used in special applications only with the express written approval of Infineon Technologies. Class III medical devices are intended to be implanted in the human body or to support and/or maintain and sustain and/or protect human life. If they fail, it is reasonable to assume that the health of the user or other persons may be endangered.

## Trademarks

### Trademarks of Infineon Technologies AG

AURIX™, C166™, CanPAK™, CIPOS™, CIPURSE™, EconoPACK™, CoolMOS™, CoolSET™, CORECONTROL™, CROSSAVE™, DAVE™, DI-POL™, EasyPIM™, EconoBRIDGE™, EconoDUAL™, EconoPIM™, EconoPACK™, EiceDRIVER™, eupec™, FCOS™, HITFET™, HybridPACK™, I<sup>2</sup>RF™, ISOFACE™, IsoPACK™, MIPAQ™, ModSTACK™, my-d™, NovalithIC™, OptiMOS™, ORIGA™, POWERCODE™, PRIMARION™, PrimePACK™, PrimeSTACK™, PRO-SIL™, PROFET™, RASIC™, ReverSave™, SatRIC™, SIEGET™, SINDRION™, SIPMOS™, SmartLEWIS™, SOLID FLASH™, TEMPFET™, thinQ!™, TRENCHSTOP™, TriCore™.

### Other Trademarks

Advance Design System™ (ADS) of Agilent Technologies, AMBA™, ARM™, MULTI-ICE™, KEIL™, PRIMECELL™, REALVIEW™, THUMB™, μVision™ of ARM Limited, UK. AUTOSAR™ is licensed by AUTOSAR development partnership. Bluetooth™ of Bluetooth SIG Inc. CAT-iq™ of DECT Forum. COLOSSUS™, FirstGPS™ of Trimble Navigation Ltd. EMV™ of EMVCo, LLC (Visa Holdings Inc.). EPCOS™ of Epcos AG. FLEXGO™ of Microsoft Corporation. FlexRay™ is licensed by FlexRay Consortium. HYPERTERMINAL™ of Hilgraeve Incorporated. IEC™ of Commission Electrotechnique Internationale. IrDA™ of Infrared Data Association Corporation. ISO™ of INTERNATIONAL ORGANIZATION FOR STANDARDIZATION. MATLAB™ of MathWorks, Inc. MAXIM™ of Maxim Integrated Products, Inc. MICROTEC™, NUCLEUS™ of Mentor Graphics Corporation. MIPI™ of MIPI Alliance, Inc. MIPS™ of MIPS Technologies, Inc., USA. muRata™ of MURATA MANUFACTURING CO., MICROWAVE OFFICE™ (MWO) of Applied Wave Research Inc., OmniVision™ of OmniVision Technologies, Inc. Openwave™ Openwave Systems Inc. RED HAT™ Red Hat, Inc. RFMD™ RF Micro Devices, Inc. SIRIUS™ of Sirius Satellite Radio Inc. SOLARIS™ of Sun Microsystems, Inc. SPANSION™ of Spansion LLC Ltd. Symbian™ of Symbian Software Limited. TAIYO YUDEN™ of Taiyo Yuden Co. TEAKLITE™ of CEVA, Inc. TEKTRONIX™ of Tektronix Inc. TOKO™ of TOKO KABUSHIKI KAISHA TA. UNIX™ of X/Open Company Limited. VERILOG™, PALLADIUM™ of Cadence Design Systems, Inc. VLYNQ™ of Texas Instruments Incorporated. VXWORKS™, WIND RIVER™ of WIND RIVER SYSTEMS, INC. ZETEX™ of Diodes Zetex Limited.

Last update

2011-11-11

[www.infineon.com](http://www.infineon.com)

## X-ON Electronics

Largest Supplier of Electrical and Electronic Components

*Click to view similar products for [IGBT Modules category](#):*

*Click to view products by [Infineon manufacturer](#):*

Other Similar products are found below :

[F3L400R07ME4\\_B22](#) [F4-50R07W2H3\\_B51](#) [FB15R06W1E3](#) [FB20R06W1E3\\_B11](#) [FD1000R33HE3-K](#) [FD400R33KF2C-K](#)  
[FD401R17KF6C\\_B2](#) [FD-DF80R12W1H3\\_B52](#) [FF200R06YE3](#) [FF300R12KE4\\_E](#) [FF450R12ME4P](#) [FF600R12IP4V](#) [FP10R06W1E3\\_B11](#)  
[FP20R06W1E3](#) [FP50R12KT3](#) [FP75R07N2E4\\_B11](#) [FS10R12YE3](#) [FS150R07PE4](#) [FS150R12PT4](#) [FS50R07N2E4\\_B11](#) [FZ1000R33HE3](#)  
[FZ1800R17KF4](#) [DD250S65K3](#) [DF1000R17IE4](#) [DF1000R17IE4D\\_B2](#) [DF1400R12IP4D](#) [DF200R12PT4\\_B6](#) [DF400R07PE4R\\_B6](#)  
[BSM75GB120DN2\\_E3223c-Se](#) [F3L300R12ME4\\_B22](#) [F3L75R07W2E3\\_B11](#) [F4-50R12KS4\\_B11](#) [F475R07W1H3B11ABOMA1](#)  
[FD1400R12IP4D](#) [FD200R12PT4\\_B6](#) [FD800R33KF2C-K](#) [FF1200R17KP4\\_B2](#) [FF300R17KE3\\_S4](#) [FF300R17ME4\\_B11](#) [FF401R17KF6C\\_B2](#)  
[FF650R17IE4D\\_B2](#) [FF900R12IP4D](#) [FF900R12IP4DV](#) [STGIF7CH60TS-L](#) [FP50R07N2E4\\_B11](#) [FS100R07PE4](#) [FS150R07N3E4\\_B11](#)  
[FS150R17N3E4](#) [FS150R17PE4](#) [FS225R12KE4](#)